<table>
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<th>APPLICATIONS</th>
<th>BENEFITS</th>
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| Used for precision slotting, singulating, slicing and dicing:  
  - Chip carrier packages (BGA, CSP, etc.)  
  - Thin-film disk drive heads  
  - Discrete electronic components such as MLCC (multi-layer ceramic capacitors)  
  - Ceramic, glass, quartz, PZT  
  - Printed circuit boards  
  - Hardened steels |  
  - Standard and custom dicing blade formulations to match your process and application  
  - Standard and custom dicing blade shapes and sizes  
  - Diamond, CBN, and conventional abrasives  
  - Excellent cut quality and dicing blade life  
  - Rapid delivery times (typically 2 weeks for custom bonds) |
FEATUERES

- Standard and custom dicing blades for use on equipment by:
  - MTI
  - Disco
  - MECO/FICO
  - Veeco
  - K&S/ADT
  - others
- Dicing blade OD: 0.5 in. to 8.0 in. (12 mm to 200 mm)
- Dicing blade thickness: As thin as 0.003 in. (0.076 mm)
- Unlimited combinations of dicing blade configurations, bond hardnesses and matrix structures
- Abrasive crystals as small as 1500 grit (1-2 µm), with tightly controlled particle size distributions (PSD)
- ITI also produces hubs, arbors, spacers and dressing plates for use with these products

ENGINEERED SOLUTIONS

ITI has standard dicing blade formulations available for many applications. In addition, ITI can custom formulate dicing blades for your specific application to maximize throughput and cut quality. Dicing blade life can be enhanced by as much as four times that of conventional dicing blades.

ITI has been producing high precision tooling since 1961. ITI products are fabricated at our 65,000 square foot facility in Oxnard, California, USA. Only the highest quality abrasive crystals and bond materials are used. Critical properties of crystals such as friability, size, shape, concentration, along with bond strength and structure are all carefully considered during the design stage to ensure optimized performance. ITI’s engineering staff is proficient in working with customers to provide the best solution for each application.